MA3X789 (MA789)

Silicon epitaxial planar type

For super high speed switching For small current rectification

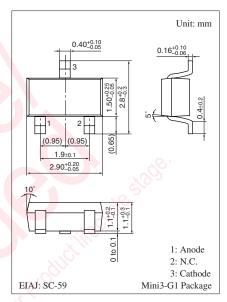
■ Features

- Forward current (Average) I_{F(AV)} = 500 mA rectification is possible
- Reverse voltage $V_R = 60 \text{ V}$ is guaranteed

■ Absolute Maximum Ratings $T_a = 25$ °C

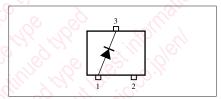
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	60	V
Maximum peak reverse voltage	V _{RM}	60	V
Forward current (Average)	I _{F(AV)}	500	mA
Non-repetitive peak forward surge current *	I_{FSM}	2	A
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



Marking Symbol: M3W

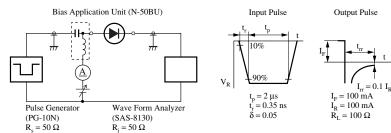
Internal Connection



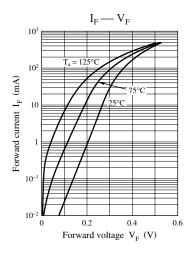
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

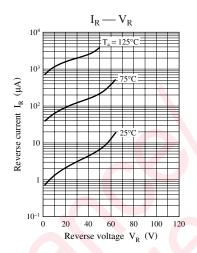
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 500 \text{ mA}$	150		0.65	V
Reverse current	I_R	V _R = 50 V			100	μΑ
Terminal capacitance	C_{t}	$V_R = 0 \text{ V, } f = 1 \text{ MHz}$		60		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		4.5		ns
		$I_{rr} = 0.1 I_{R}, R_{L} = 100 \Omega$				

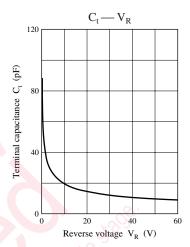
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 100 MHz.
- 4. *: t_{rr} measurement circuit

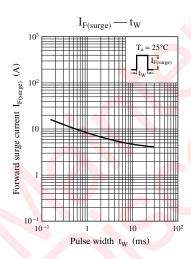


Note) The part number in the parenthesis shows conventional part number.









2 SKH00089CED

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